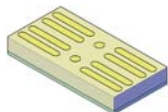


# MECHANICAL CASE OUTLINE

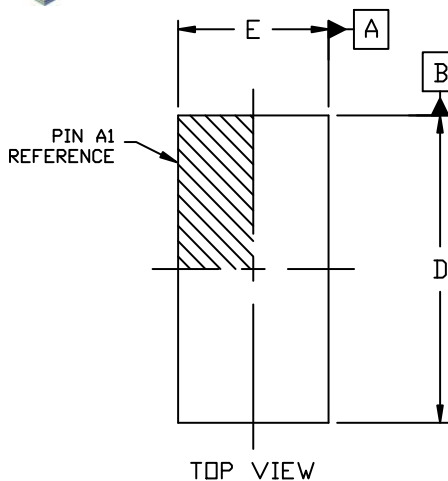
## PACKAGE DIMENSIONS

ON Semiconductor®



**WLCSP10, 3.54x1.77x0.14**  
**CASE 567XB**  
**ISSUE O**

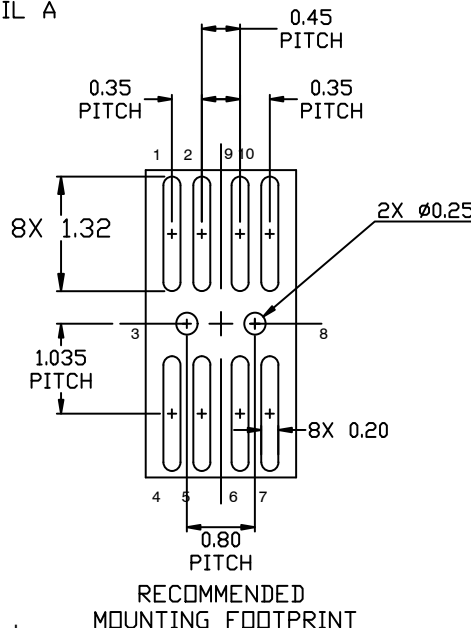
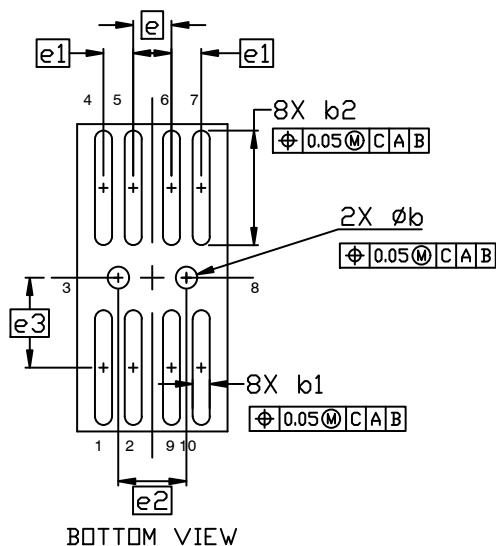
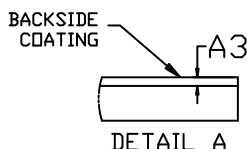
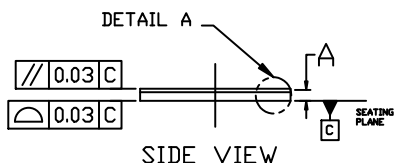
DATE 09 OCT 2018



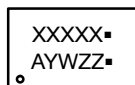
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.11	0.14	0.17
A3	0.04 REF		
b	0.22	0.25	0.28
b1	0.17	0.20	0.23
b2	1.29	1.32	1.35
D	3.51	3.54	3.57
E	1.74	1.77	1.80
e	0.45 BSC		
e1	0.35 BSC		
e2	0.80 BSC		
e3	1.035 BSC		



### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
 A = Assembly Location  
 Y = Year  
 W = Work Week  
 ZZ = Assembly Lot Code  
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>WLCSP10, 3.54x1.77x0.14</b>	<b>PAGE 1 OF 1</b>

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